

REMARKS

Please reconsider the application in view of the above amendments and the following remarks. Applicant thanks the Examiner for carefully considering this application.

Disposition of Claims

Claims 1-2 are pending in this application. Claim 1 is independent, and claim 2 depends from claim 1. Claims 3-10 have been withdrawn from consideration.

Restriction Requirement

Applicant hereby acknowledges that claims 3-10 are withdrawn from consideration due to a provisional election made in response to a restriction requirement to prosecute the invention of Group I, claims 1 and 2, on January 20, 2004 in a telephone conversation.

Specification

The Abstract is amended to conform to the Examiner's requirement. Accordingly, withdrawal of this objection is respectfully requested.

Rejection(s) under 35 U.S.C § 102

Claims 1-2 stand rejected under 35 U.S.C. § 102(e) as anticipated by U.S. Patent No. 6,320,135 ("Saito"). This the rejection is respectfully traversed.

The present invention relates to manufacturing a wiring substrate by arranging multiple identical wiring patterns in a predetermined direction on the substrate. Claim 1 recites a stock sheet for a flexible wiring board that comprises a flexible sheet-like substrate

and a plurality of wiring patterns that are arranged in a predetermined direction on the substrate and corresponding to patterns on individual layers of wiring boards of a multilayer flexible wiring board.

According to embodiments of the invention, the thickness of the substrate scarcely varies between the individual layers of the wiring boards. The dimensional changes in individual layers during the manufacturing process can be homogenized because a plurality of wiring patterns corresponding to the individual layers of wiring boards of a multilayer flexible wiring board are arranged on the same substrate. As a result, the present invention allows connecting electrodes on individual layers of wiring boards to be precisely positioned, thereby allowing the individual layers of wiring boards to be readily stacked. (See specification p. 6, l. 4 through p. 7, l. 5).

Claim 2 recites that each wiring pattern is arranged in a direction perpendicular to a transporting direction of the substrate. In addition, the variation in the thickness of the substrate or the like with different product lots can be minimized because the wiring patterns are arranged in a direction perpendicular to the transporting direction of the substrate. (See specification p. 7, ll. 6–9). Saito, on the other hand, discloses a predetermined wiring formed on a base film. Saito discusses a wiring pattern substrate that is formed when a copper layer is etched. In contrast to the present invention, as recited in amended claim 2, Saito fails to disclose that the wiring placed on the substrate (*i.e.*, the base film) is in a direction perpendicular to the wiring substrate. Further, Saito fails to disclose that the wiring substrate is “transported” in a particular direction.

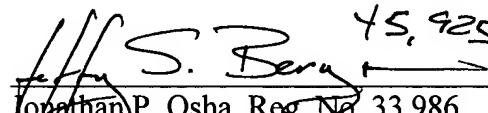
In view of the above, Saito fails to show or suggest the present invention as recited in the claims. Thus, the claims are patentable over Saito. Accordingly, withdrawal of this

rejection is respectfully requested.

Applicant believes this reply is fully responsive to all outstanding issues and places this application in condition for allowance. If this belief is incorrect, or other issues arise, the Examiner is encouraged to contact the undersigned or his associates at the telephone number listed below. Please apply any charges not covered, or any credits, to Deposit Account 50-0591 (Reference Number 03310.023001).

Respectfully submitted,

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